

APR 20 2007

PATENT

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Eugene A. Pruss, et al.

Title: BORON NITRIDE AGGLOMERATED POWDER

App. No.: 10/645,305

Filed: 08/21/2003

Examiner: Wayne A. Langel

Group Art Unit: 1754

Atty. Dkt. No.: 1035-BN4126

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Mail Stop AMENDMENT  
Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

## REQUEST FOR RECONSIDERATION

Dear Sir:

In response to the Office Action mailed December 20, 2006, reconsideration and withdrawal of the Section 102(b)/ Section 103 Rejection over Hagio et al. are respectfully requested for the following reasons.

As discussed in Applicants' previous response, the claimed invention has been developed to address deficiencies with state of the art boron nitride powders that have various commercial uses, notably for use as a thermal filler in high performance thermal interface materials used in the electronics industry. It is generally desired that such fillers have high thermal conductivity, low electrical conductivity, and enhanced thermal conductivity under low loading levels. The claimed invention provides an agglomerated powder that combines features of low density and high strength. Stated alternatively, the claimed boron nitride agglomerated powder has a high fracture strength to tap density ratio, particularly, not less than 11 Mpa cc/g.

The PTO correctly points out that among the various features that contribute to the achievement of a powder formed of agglomerates having high strength and low density, a classified, agglomerated feedstock powder is subjected to heat treatment. In this respect, Applicants emphasize two points. First, the agglomerated powder is preferably formed through a